



产品规格书/Specification

产品/product:	氧化铝陶瓷发热电阻浆料/ Alumina ceramic board heating Resist paste
料号/Part number:	55H18

适用范围/Application:

此产品适用于氧化铝陶瓷加热电路使用。

The resist paste applies to alumina ceramic heating resistor paste.

使用条件/Operating conditions:

基材 Substrate	氧化铝陶瓷 Alumina ceramic
印刷 Printing	200-250 目丝网印刷 200-250 mesh stainless screen
流平 Levelling	室温下流平 5-15 分钟 (时间根据流平的实际情况决定)。 5-15min minutes at room temperature
干燥 Drying	通风烘箱烘烤 100-150°C, 10-15 分钟 (烘烤温度低于 300°C, 可根据烘烤的实际情况决定烘烤时间。) 100-150°C 10-15 min
烧结 Firing Condition	隧道炉空气气氛下烧结, 峰值 850°C (推荐值), 10 分钟。 Atmospheric firing in belt furnace with peak time of 10 Minutes at 850°C
Thinner	ST1001

性能/Characteristics:

1. 浆料性能/Paste Characteristics:

性能 Characteristic	标准 Standard	测试方法及条件 Test method and conditions
1 Fineness	≤8μm	FOG test
2 Viscosity	120-280Pa.s	Brookfield HBT utility cup and spindle (SC4-14/6R), 10rpm, 25±1°C, Brookfield HBT (博利飞) 粘度计, 转子 SC4-14/6R), 10rpm, 25±1°C 粘度可根据用户实际需要调节。

2. 烧结后特性/Characteristics after firing:

在 1 烧结条件下, 膜厚 8-12μm Check fired film produced under the conditions specified in 1), (Film thickness is 8-12μm.)



特性 Characteristics	Standard 标准	测试方法和条件 Test method and conditions
3 外观 Appearance	紧凑, 致密 Compact and unknit	Eyeballing
4 方阻值 Resistivity	如下表格 As below form	标准膜厚 10 μ m Standard film thickness is 10μm.
	温度系数 TCR	如下表格 As below form HTCR 25-125°C

产品系列	氧化铝陶瓷发热电阻浆料 Alumina ceramic board heating Resist paste			
P/N	Resistivity (Ω/□)	TCR (ppm/°C)	烧结温度°C Sintering	Viscosity (kcps)
55H18-0R03030	0.03	3000	850	150-300
55H18-0R04030	0.04	3000		
55H18-0R05030	0.05	3000		

保存条件, 有效期/Storage condition and Term of validity

产品应在 5-25°C 的环境温度下密封储存, 有效期为产品发货之日起六个月。

包装方式/Packaging method:

1000g/罐, 1000g/can